

# MOSFET - SiC Power, Single N-Channel, TO247-4L 650 V, 44 m $\Omega$ , 47 A

# **NVH4L060N065SC1**

#### **Features**

- Typ.  $R_{DS(on)} = 44 \text{ m}\Omega$  @  $V_{GS} = 18 \text{ V}$ Typ.  $R_{DS(on)} = 60 \text{ m}\Omega$  @  $V_{GS} = 15 \text{ V}$
- Ultra Low Gate Charge  $(Q_{G(tot)} = 74 \text{ nC})$
- Low Capacitance (C<sub>oss</sub> = 133 pF)
- 100% Avalanche Tested
- AEC-Q101 Qualified and PPAP Capable
- This Device is Pb-Free and is RoHS Compliant

#### **Typical Applications**

- Automotive On Board Charger
- Automotive DC/DC Converter for EV/HEV

#### MAXIMUM RATINGS (T<sub>J</sub> = 25°C unless otherwise noted)

Parameter			Value	Unit
Drain-to-Source Voltage			650	V
)		$V_{GS}$	-8/+22	V
Recommended Operation Values of Gate-to-Source Voltage		$V_{GSop}$	-5/+18	V
Steady State	T <sub>C</sub> = 25°C	I <sub>D</sub>	47	Α
		P <sub>D</sub>	176	W
Steady State	T <sub>C</sub> = 100°C	I <sub>D</sub>	33	Α
		P <sub>D</sub>	88	W
T <sub>C</sub> = 25°C		I <sub>DM</sub>	152	Α
Operating Junction and Storage Temperature Range			-55 to +175	°C
Source Current (Body Diode)			35	Α
Single Pulse Drain-to-Source Avalanche Energy (I <sub>L(pk)</sub> = 10.1 A, L = 1 mH) (Note 3)			51	mJ
Maximum Lead Temperature for Soldering (1/8" from case for 5 s)		TL	260	°C
	Steady State  Storage To  Stor	on Values on Values age $T_C < 175^{\circ}C$ age $T_C = 25^{\circ}C$ Steady $T_C = 100^{\circ}C$ State $T_C = 25^{\circ}C$ Storage Temperature siode)  Source Avalanche $T_C = T_C = T_$	$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	$\begin{array}{c ccccccccccccccccccccccccccccccccccc$

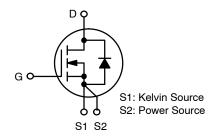
Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

 The entire application environment impacts the thermal resistance values shown, they are not constants and are only valid for the particular conditions noted.

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- 2. Repetitive rating, limited by max junction temperature.
- 3. EAS of 51 mJ is based on starting  $T_J = 25^{\circ}C$ ; L = 1 mH,  $I_{AS} = 10.1$  A,  $V_{DD} = 50$  V,  $V_{GS} = 18$  V.

V <sub>(BR)DSS</sub>	R <sub>DS(ON)</sub> MAX	I <sub>D</sub> MAX		
650 V	70 mΩ @ 18 V	47 A		

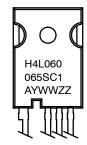


**N-CHANNEL MOSFET** 



TO247-4L CASE 340CJ

#### **MARKING DIAGRAM**



H4L060065SC1 = Specific Device Code

A = Assembly Location

Y = Year

WW = Work Week

ZZ = Lot Traceability

# ORDERING INFORMATION

Device	Package	Shipping
NVH4L060N065SC1	TO247-4L	30 Units / Tube

# THERMAL RESISTANCE MAXIMUM RATINGS

Parameter	Symbol	Max	Unit
Junction-to-Case - Steady State (Note 1)	$R_{ heta JC}$	0.85	°C/W
Junction-to-Ambient - Steady State (Note 1)	$R_{\theta JA}$	40	

# **ELECTRICAL CHARACTERISTICS** (T<sub>J</sub> = 25°C unless otherwise specified)

Parameter	Symbol	Test Condition		Min	Тур	Max	Unit
OFF CHARACTERISTICS							
Drain-to-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	$V_{GS} = 0 \text{ V}, I_D = 1 \text{ mA}$		650	_	-	V
Drain-to-Source Breakdown Voltage Temperature Coefficient	V <sub>(BR)DSS</sub> /T <sub>J</sub>	I <sub>D</sub> = 20 mA, referenced to 25°C		-	0.15	-	V/°C
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>GS</sub> = 0 V, T <sub>J</sub> = 25°C		-	_	10	μΑ
		V <sub>DS</sub> = 650 V	T <sub>J</sub> = 175°C	-	-	1	mA
Gate-to-Source Leakage Current	I <sub>GSS</sub>	$V_{GS} = +18/-5 \text{ V}, \text{ V}$	V <sub>DS</sub> = 0 V	-	_	250	nA
ON CHARACTERISTICS (Note 2)	•					•	
Gate Threshold Voltage	V <sub>GS(TH)</sub>	$V_{GS} = V_{DS}, I_D =$	6.5 mA	1.8	2.8	4.3	V
Recommended Gate Voltage	V <sub>GOP</sub>			-5	-	+18	V
Drain-to-Source On Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 15 V, I <sub>D</sub> = 20 A	A, T <sub>J</sub> = 25°C	1	60	_	mΩ
		V <sub>GS</sub> = 18 V, I <sub>D</sub> = 20 A	A, T <sub>J</sub> = 25°C	_	44	70	
		V <sub>GS</sub> = 18 V, I <sub>D</sub> = 20 A	A, T <sub>J</sub> = 175°C	1	50	_	
Forward Transconductance	9FS	V <sub>DS</sub> = 10 V, I <sub>D</sub>	= 20 A	1	12	_	S
CHARGES, CAPACITANCES & GATE RES	SISTANCE					•	
Input Capacitance	C <sub>ISS</sub>	V <sub>GS</sub> = 0 V, f = 1 MHz, V <sub>DS</sub> = 325 V		-	1473	_	pF
Output Capacitance	C <sub>OSS</sub>			_	133	_	
Reverse Transfer Capacitance	C <sub>RSS</sub>			-	13	-	
Total Gate Charge	Q <sub>G(TOT)</sub>	$V_{GS} = -5/18 \text{ V}, V_{DS} = 520 \text{ V},$ $I_{D} = 20 \text{ A}$		1	74	-	nC
Gate-to-Source Charge	$Q_{GS}$			1	20	-	
Gate-to-Drain Charge	$Q_{GD}$			1	23	-	
Gate-Resistance	$R_{G}$	f = 1 MHz		1	3.9	_	Ω
SWITCHING CHARACTERISTICS							
Turn-On Delay Time	t <sub>d(ON)</sub>	$\begin{array}{l} V_{GS} = -5/18 \text{ V,} \\ V_{DS} = 400 \text{ V,} \\ I_{D} = 20 \text{ A,} \\ R_{G} = 2.2 \Omega \\ \text{inductive load} \end{array}$		-	11	_	ns
Rise Time	t <sub>r</sub>			-	14	_	
Turn-Off Delay Time	t <sub>d(OFF)</sub>			-	24	-	
Fall Time	t <sub>f</sub>			1	11	-	
Turn-On Switching Loss	E <sub>ON</sub>	- - -		-	45	-	μJ
Turn-Off Switching Loss	E <sub>OFF</sub>			-	18	-	
Total Switching Loss	E <sub>tot</sub>			-	63	_	
DRAIN-SOURCE DIODE CHARACTERIST	ics						
Continuous Drain-Source Diode Forward Current	I <sub>SD</sub>	V <sub>GS</sub> = -5 V, T <sub>J</sub> = 25°C		-	-	35	Α
Pulsed Drain-Source Diode Forward Current (Note 2)	I <sub>SDM</sub>			-	-	152	
Forward Diode Voltage	V <sub>SD</sub>	$V_{GS} = -5 \text{ V}, I_{SD} = 20$	A, T <sub>J</sub> = 25°C	-	4.3	_	V

# **ELECTRICAL CHARACTERISTICS** ( $T_J = 25^{\circ}C$ unless otherwise specified) (continued)

`	· ·	1 / 1				
Parameter	Symbol	Test Condition	Min	Тур	Max	Unit
DRAIN-SOURCE DIODE CHARACTERIST	rics					
Reverse Recovery Time	t <sub>RR</sub>	$V_{GS} = -5/18 \text{ V}, I_{SD} = 20 \text{ A},$ $dI_S/dt = 1000 \text{ A}/\mu\text{s}$	_	17.7	-	ns
Reverse Recovery Charge	$Q_{RR}$	dI <sub>S</sub> /dt = 1000 A/μs	_	90.6	-	nC
Reverse Recovery Energy	E <sub>REC</sub>		_	8.7	-	μJ
Peak Reverse Recovery Current	I <sub>RRM</sub>		_	10.2	-	Α
Charge time	Ta	1	_	9.8	-	ns
Discharge time	Tb	1	_	7.8	-	ns

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

#### **TYPICAL CHARACTERISTICS**

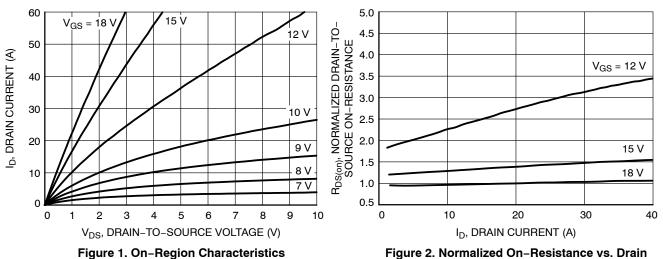


Figure 1. On-Region Characteristics

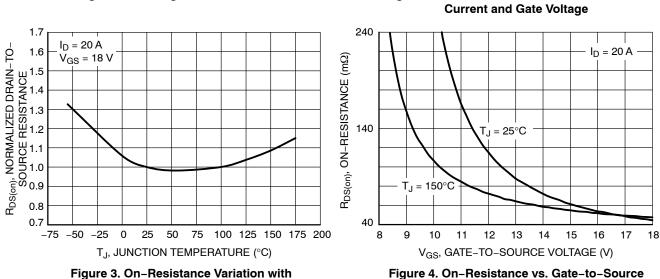


Figure 3. On-Resistance Variation with Temperature

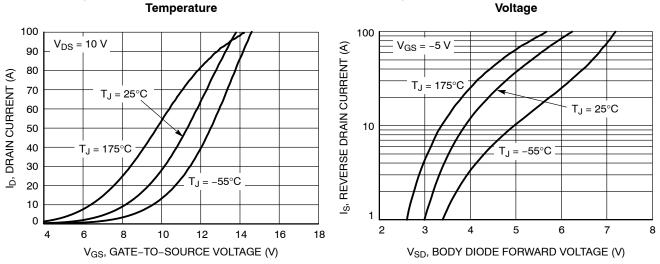
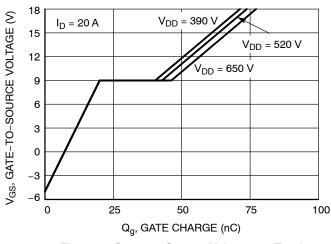


Figure 5. Transfer Characteristics

Figure 6. Diode Forward Voltage vs. Current

#### **TYPICAL CHARACTERISTICS**



10000

(d) 1000

(d) 1000

(e) 1000

(f = 1 MHz

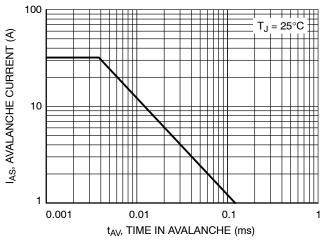
V<sub>GS</sub> = 0 V

0.1 1 10 100

V<sub>DS</sub>, DRAIN-TO-SOURCE VOLTAGE (V)

Figure 7. Gate-to-Source Voltage vs. Total Charge

Figure 8. Capacitance vs. Drain-to-Source Voltage



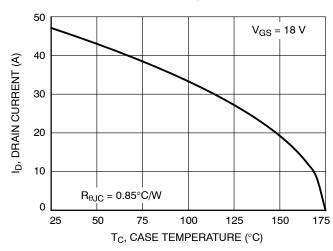
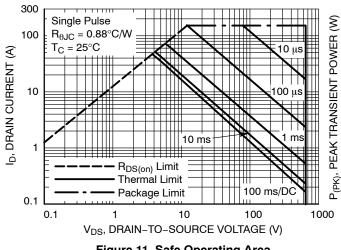


Figure 9. Unclamped Inductive Switching Capability

Figure 10. Maximum Continuous Drain Current vs. Case Temperature



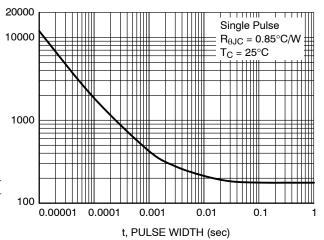


Figure 11. Safe Operating Area

Figure 12. Single Pulse Maximum Power Dissipation

# **TYPICAL CHARACTERISTICS**

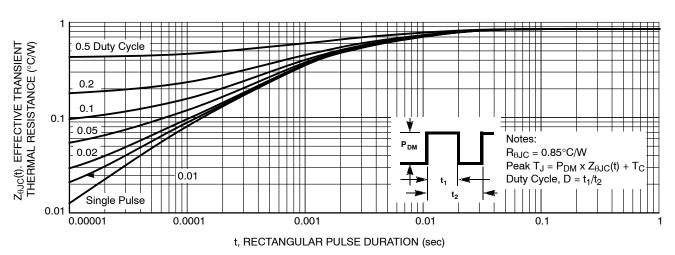
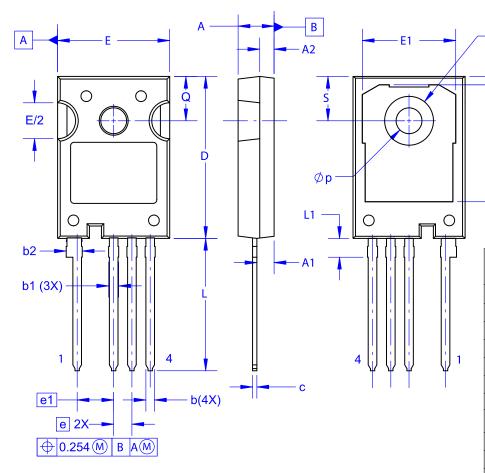


Figure 13. Junction-to-Case Thermal Response

# **PACKAGE DIMENSIONS**

TO-247-4LD CASE 340CJ ISSUE A



#### NOTES:

- A. NO INDUSTRY STANDARD APPLIES TO THIS PACKAGE.
  B. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD
  FLASH, AND TIE BAR EXTRUSIONS.
  C. ALL DIMENSIONS ARE IN MILLIMETERS.
  D. DRAWING CONFORMS TO ASME Y14.5-2009.

DIM	MIL	LIMETER	S			
DIM	MIN	NOM	MAX			
Α	4.80	5.00	5.20			
A1	2.10	2.40	2.70			
A2	1.80	2.00	2.20			
b	1.07	1.20	1.33			
b1	1.20	1.40	1.60			
b2	2.02	2.22	2.42			
С	0.50	0.60	0.70			
D	22.34	22.54	22.74			
D1	16.00	16.25	16.50			
D2	0.97	1.17	1.37			
е	2.54 BSC					
e1	5.08 BSC					
E	15.40	15.80				
E1	12.80	13.00	13.20			
E/2	4.80	5.00	5.20			
L	18.22	18.42	18.62			
L1	2.42	2.62	2.82			
р	3.40	3.60	3.80			
p1	6.60	6.80	7.00			
Q	5.97	6.17	6.37			
S	5.97	6.17	6.37			

Ø**p1** 

D1

D2

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